

CS5201-3

1.0 A, 3.3 V Fixed Linear Regulator

The CS5201-3 linear regulator provides 1.0 A @ 3.3 V reference at 1.0 A with an output voltage accuracy of $\pm 1.5\%$.

This regulator is intended for use as a post regulator and microprocessor supply. The fast loop response and low dropout voltage make this regulator ideal for applications where low voltage operation and good transient response are important.

The circuit is designed to operate with dropout voltages less than 1.2 V at 1.0 A output current.

The maximum quiescent current is only 10 mA at full load. Device protection includes over-current and thermal shutdown.

The CS5201-3 is pin compatible with the LT1086 family of linear regulators.

The regulator is available in TO-220, surface mount D², and SOT-223 packages.

Features

- Output Current to 1.0 A
- Output Accuracy to $\pm 1.5\%$ Over Temperature
- Dropout Voltage (typical) 1.0 V @ 1.0 A
- Fast Transient Response
- Fault Protection
 - Current Limit
 - Thermal Shutdown

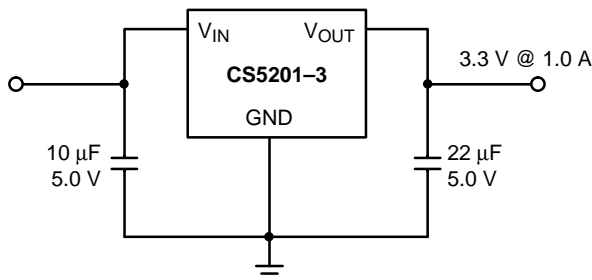
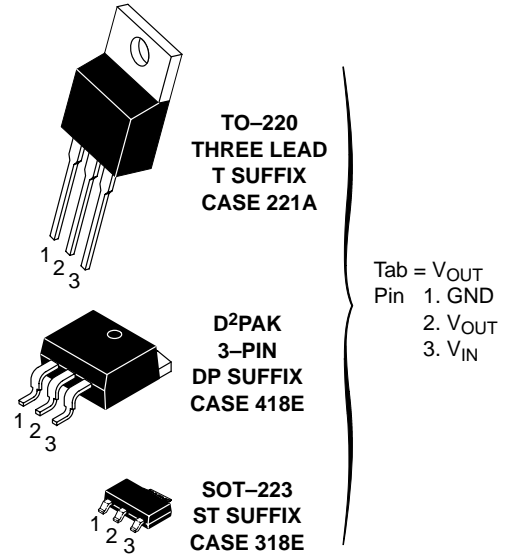


Figure 1. Applications Diagram



ON Semiconductor®

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ORDERING INFORMATION*†

Device	Package	Shipping
CS5201-3GT3	TO-220‡	50 Units/Rail
CS5201-3GDP3	D ² PAK‡	50 Units/Rail
CS5201-3GDPR3	D ² PAK‡	750 Tape & Reel
CS5201-3GST3	SOT-223‡	80 Units/Rail
CS5201-3GSTR3	SOT-223‡	2500 Tape & Reel

*Additional ordering information can be found on page 6 of this data sheet.

†Consult your local sales representative for other fixed output voltage versions.

‡TO-220 are all 3-pin, straight leaded. D²PAK and SOT-223 are all 3-pin.

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 6 of this data sheet.

CS5201-3

MAXIMUM RATINGS*

Parameter	Value	Unit	
Supply Voltage, V_{IN}	7.0	V	
Operating Temperature Range	-40 to +70	°C	
Junction Temperature	150	°C	
Storage Temperature Range	-60 to +150	°C	
Lead Temperature Soldering:	Wave Solder (through hole styles only) Note 1 Reflow (SMD styles only) Note 2	260 Peak 230 Peak	°C °C
ESD Damage Threshold (Human Body Model)	2.0	kV	

1. 10 second maximum.

2. 60 second maximum above 183°C

*The maximum package power dissipation must be observed.

ELECTRICAL CHARACTERISTICS ($C_{IN} = 10 \mu\text{F}$, $C_{OUT} = 22 \mu\text{F}$ Tantalum, $V_{OUT} + V_{DROPOUT} < V_{IN} < 7.0 \text{ V}$, $0^\circ\text{C} \leq T_A \leq 70^\circ\text{C}$, $T_J \leq +150^\circ\text{C}$, unless otherwise specified, $I_{full\ load} = 1.0 \text{ A}$)

Characteristic	Test Conditions	Min	Typ	Max	Unit
Fixed Output Voltage					
Reference Voltage (Notes 3 and 4)	$V_{IN} - V_{OUT} = 1.5 \text{ V}$; $0 \leq I_{OUT} \leq 1.0 \text{ A}$	3.250 (-1.5%)	3.300	3.350 (+1.5%)	V
Line Regulation	$2.0 \text{ V} \leq V_{IN} - V_{OUT} \leq 3.7 \text{ V}$; $I_{OUT} = 10 \text{ mA}$	-	0.02	0.20	%
Load Regulation (Notes 3 and 4)	$V_{IN} - V_{OUT} = 2.0 \text{ V}$; $10 \text{ mA} \leq I_{OUT} \leq 1.0 \text{ A}$	-	0.04	0.4	%
Dropout Voltage (Note 5)	$I_{OUT} = 1.0 \text{ A}$	-	1.0	1.2	V
Current Limit	$V_{IN} - V_{OUT} = 3.0 \text{ V}$	1.0	3.1	-	A
Quiescent Current	$I_{OUT} = 10 \text{ mA}$	-	5.0	10	mA
Thermal Regulation (Note 6)	30 ms Pulse, $T_A = 25^\circ\text{C}$	-	0.002	0.020	%/W
Ripple Rejection (Note 6)	$f = 120 \text{ Hz}$; $I_{OUT} = 1.0 \text{ A}$; $V_{IN} - V_{OUT} = 3.0 \text{ V}$; $V_{RIPPLE} = 1.0 \text{ V}_{PP}$	-	80	-	dB
Thermal Shutdown (Note 7)	-	150	180	210	°C
Thermal Shutdown Hysteresis (Note 7)	-	-	25	-	°C

3. Load regulation and output voltage are measured at a constant junction temperature by low duty cycle pulse testing. Changes in output voltage due to temperature changes must be taken into account separately.

4. Specifications apply for an external Kelvin sense connection at a point on the output pin 1/4" from the bottom of the package.

5. Dropout voltage is a measurement of the minimum input/output differential at full load.

6. Guaranteed by design, not 100% tested in production.

7. Thermal shutdown is 100% functionally tested in production.

PACKAGE PIN DESCRIPTION

Package Pin Number			Pin Symbol	Function
TO-220	D ² PAK	SOT-223		
1	1	1	GND	Ground connection.
2	2	2	V_{OUT}	Regulated output voltage (case).
3	3	3	V_{IN}	Input voltage.

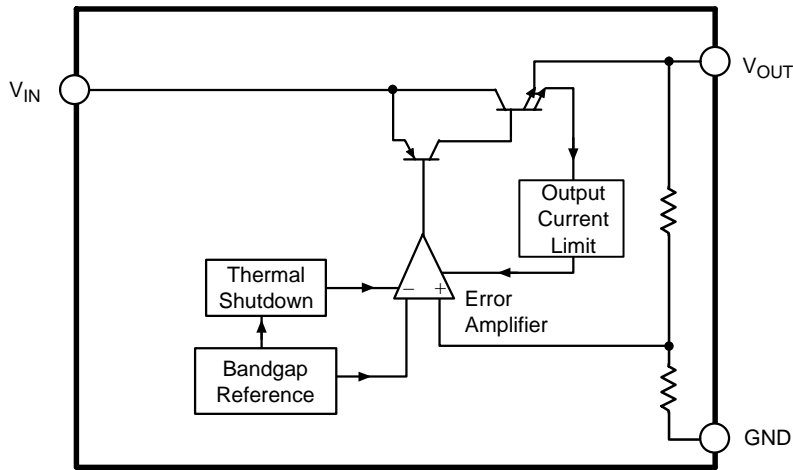


Figure 2. Block Diagram

TYPICAL PERFORMANCE CHARACTERISTICS

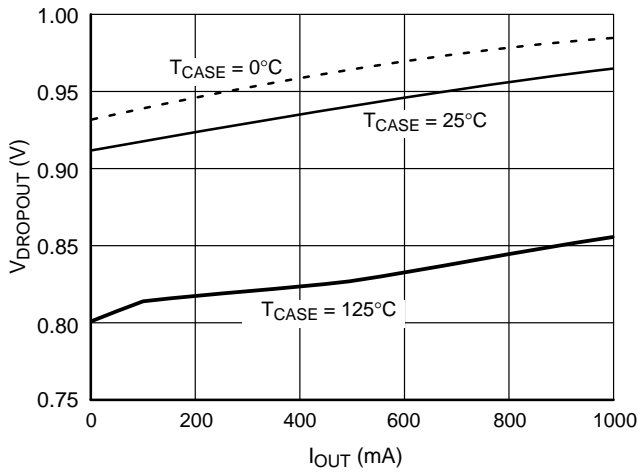


Figure 3. Dropout Voltage vs. Output Current

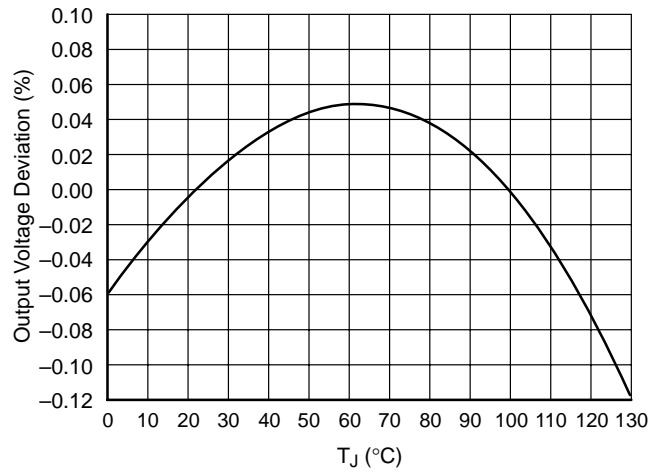


Figure 4. Reference Voltage vs. Temperature

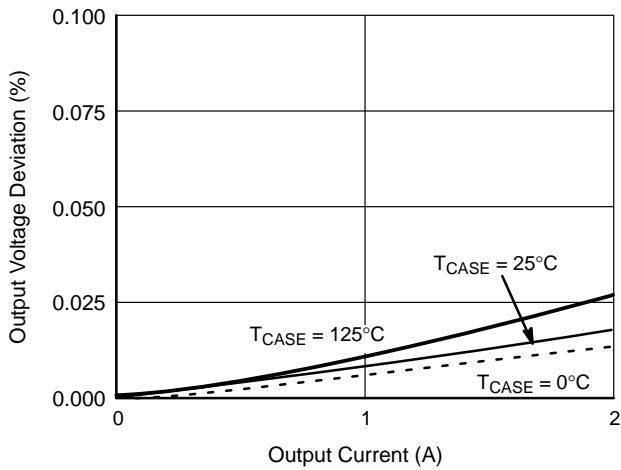


Figure 5. Load Regulation vs. Output Current

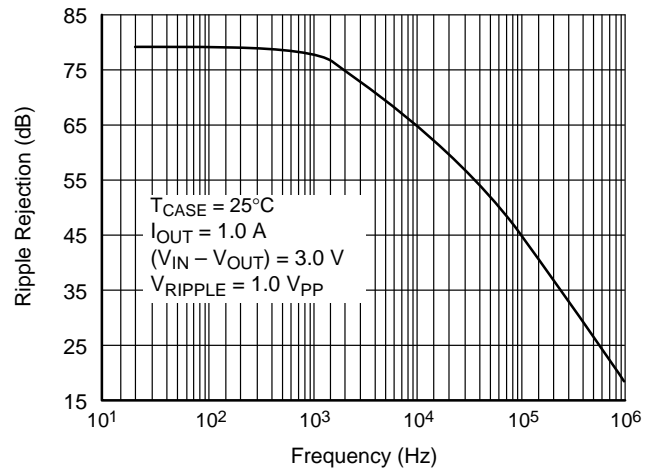


Figure 6. Ripple Rejection vs. Frequency

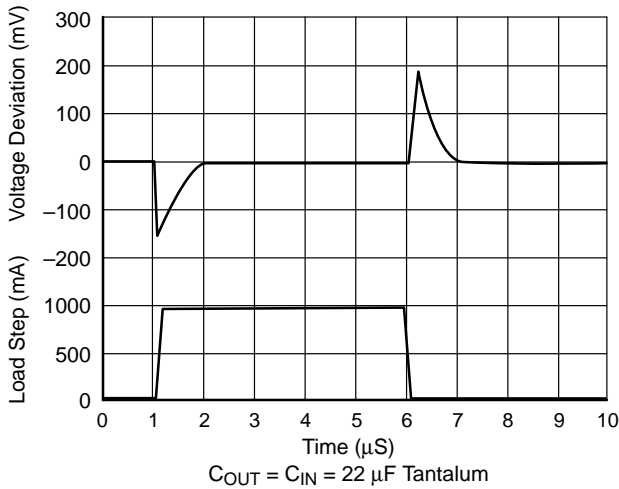


Figure 7. Transient Response

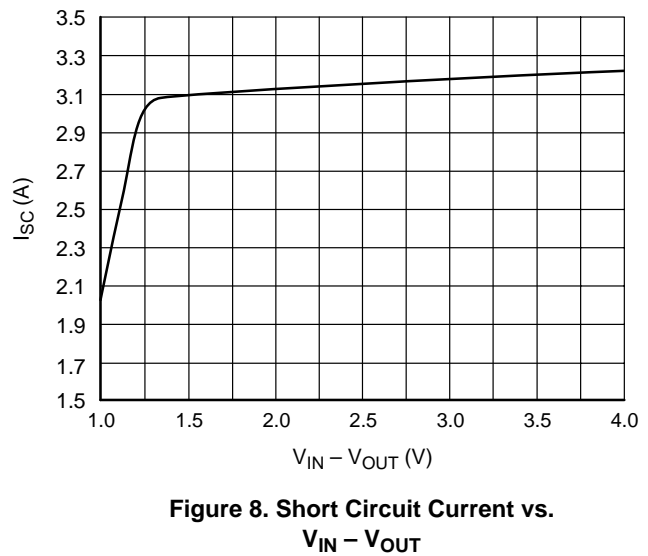


Figure 8. Short Circuit Current vs. $V_{IN} - V_{OUT}$

APPLICATIONS INFORMATION

The CS5201-3 linear regulator provides a fixed 3.3 V output voltage at currents up to 1.0 A. The regulator is protected against overcurrent conditions and includes thermal shutdown.

The CS5201-3 has a composite PNP-NPN output transistor and requires an output capacitor for stability. A detailed procedure for selecting this capacitor is included in the Stability Considerations section.

Stability Considerations

The output compensation capacitor helps determine three main characteristics of a linear regulator: start-up delay, load transient response, and loop stability.

The capacitor value and type is based on cost, availability, size and temperature constraints. A tantalum or aluminum electrolytic capacitor is best, since a film or ceramic capacitor with almost zero ESR can cause instability. The aluminum electrolytic capacitor is the least expensive solution. However, when the circuit operates at low temperatures, both the value and ESR of the capacitor will vary considerably. The capacitor manufacturer’s data sheet provides this information.

A 22 μF tantalum capacitor will work for most applications, but with high current regulators such as the CS5201-3 the transient response and stability improve with higher values of capacitance. The majority of applications for this regulator involve large changes in load current so the output capacitor must supply the instantaneous load current. The ESR of the output capacitor causes an immediate drop in output voltage given by:

$$\Delta V = \Delta I \times ESR$$

For microprocessor applications it is customary to use an output capacitor network consisting of several tantalum and

ceramic capacitors in parallel. This reduces the overall ESR and reduces the instantaneous output voltage drop under transient load conditions. The output capacitor network should be as close to the load as possible for the best results.

Protection Diodes

When large external capacitors are used with a linear regulator it is sometimes necessary to add protection diodes. If the input voltage of the regulator gets shorted, the output capacitor will discharge into the output of the regulator. The discharge current depends on the value of the capacitor, the output voltage and the rate at which V_{IN} drops. In the CS5201-3 linear regulator, the discharge path is through a large junction and protection diodes are not usually needed. If the regulator is used with large values of output capacitance and the input voltage is instantaneously shorted to ground, damage can occur. In this case, a diode connected as shown in Figure 9 is recommended.

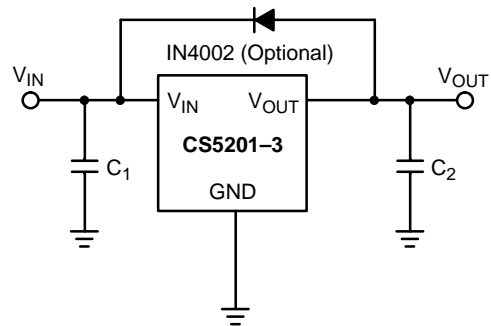


Figure 9. Protection Diode Scheme for Large Output Capacitors

Output Voltage Sensing

Since the CS5201-3 is a three terminal regulator, it is not possible to provide true remote load sensing. Load regulation is limited by the resistance of the conductors connecting the regulator to the load. For best results the regulator should be connected as shown in Figure 10.

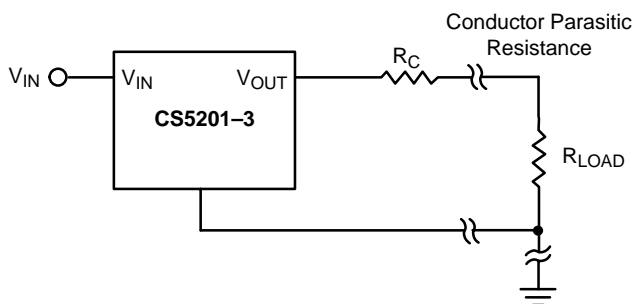


Figure 10. Conductor Parasitic Resistance Effects Can Be Minimized With the Above Grounding Scheme For Fixed Output Regulators

Calculating Power Dissipation and Heat Sink Requirements

The CS5201-3 linear regulator includes thermal shutdown and current limit circuitry to protect the device. High power regulators such as these usually operate at high junction temperatures so it is important to calculate the power dissipation and junction temperatures accurately to ensure that an adequate heat sink is used.

The case is connected to VOUT on the CS5201-3, electrical isolation may be required for some applications. Thermal compound should always be used with high current regulators such as these.

The thermal characteristics of an IC depend on the following four factors:

1. Maximum Ambient Temperature TA (°C)
2. Power dissipation PD (Watts)
3. Maximum junction temperature TJ (°C)
4. Thermal resistance junction to ambient RθJA (°C/W)

These four are related by the equation

$$T_J = T_A + P_D \times R_{\theta JA} \quad (1)$$

The maximum ambient temperature and the power dissipation are determined by the design while the maximum junction temperature and the thermal resistance depend on the manufacturer and the package type.

The maximum power dissipation for a regulator is:

$$P_{D(max)} = \{V_{IN(max)} - V_{OUT(min)}\}I_{OUT(max)} + V_{IN(max)}I_Q \quad (2)$$

where:

- VIN(max) is the maximum input voltage,
- VOUT(min) is the minimum output voltage,
- IOUT(max) is the maximum output current, for the application
- IQ is the maximum quiescent current at IOUT(max).

A heat sink effectively increases the surface area of the package to improve the flow of heat away from the IC and into the surrounding air.

Each material in the heat flow path between the IC and the outside environment has a thermal resistance. Like series electrical resistances, these resistances are summed to determine RθJA, the total thermal resistance between the junction and the surrounding air.

1. Thermal Resistance of the junction to case, RθJC (°C/W)
2. Thermal Resistance of the case to Heat Sink, RθCS (°C/W)
3. Thermal Resistance of the Heat Sink to the ambient air, RθSA (°C/W)

These are connected by the equation:

$$R_{\theta JA} = R_{\theta JC} + R_{\theta CS} + R_{\theta SA} \quad (3)$$

The value for RθJA is calculated using equation (3) and the result can be substituted in equation (1).

The value for RθJC is 3.5°C/W for a given package type based on an average die size. For a high current regulator such as the CS5201-3 the majority of the heat is generated in the power transistor section. The value for RθSA depends on the heat sink type, while RθCS depends on factors such as package type, heat sink interface (is an insulator and thermal grease used?), and the contact area between the heat sink and the package. Once these calculations are complete, the maximum permissible value of RθJA can be calculated and the proper heat sink selected. For further discussion on heat sink selection, see application note “Thermal Management,” document number AND8036/D, available through the Literature Distribution Center or via our website at <http://onsemi.com>.

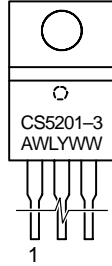
CS5201-3

ADDITIONAL ORDERING INFORMATION

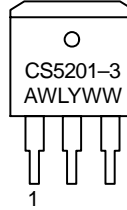
Orderable Part Number	Type	Description
CS5201-3GT3	1.0 A, 3.3 V Output	TO-220 THREE LEAD, STRAIGHT
CS5201-3GDP3	1.0 A, 3.3 V Output	D ² PAK 3-PIN
CS5201-3GDPR3	1.0 A, 3.3 V Output	D ² PAK 3-PIN (Tape & Reel)
CS5201-3GST3	1.0 A, 3.3 V Output	SOT-223
CS5201-3GSTR3	1.0 A, 3.3 V Output	SOT-223 (Tape & Reel)

MARKING DIAGRAMS

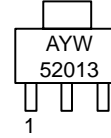
**TO-220
THREE LEAD
T SUFFIX
CASE 221A**



**D²PAK
3-PIN
DP SUFFIX
CASE 418E**



**SOT-223
ST SUFFIX
CASE 318E**

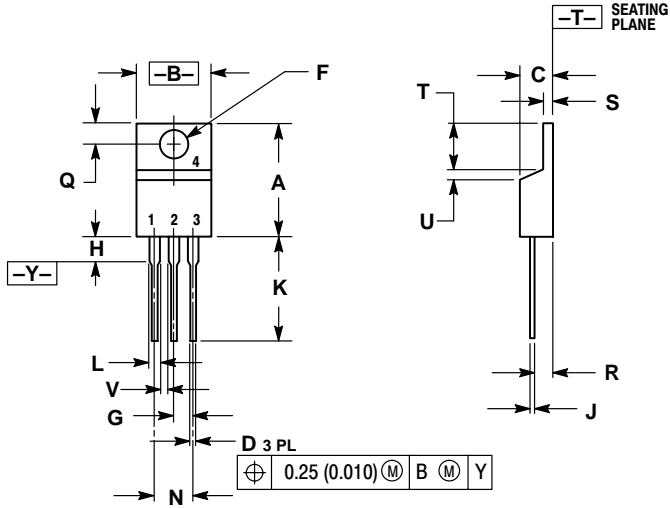


A = Assembly Location
 WL, L = Wafer Lot
 YY, Y = Year
 WW, W = Work Week

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PACKAGE DIMENSIONS

TO-220
THREE LEAD
T SUFFIX
CASE 221A-08
ISSUE AA

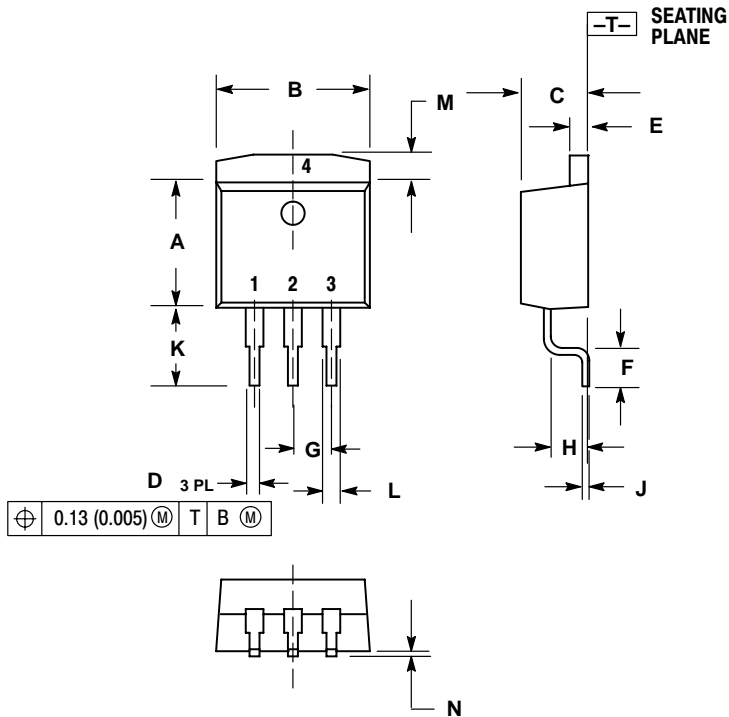


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.560	0.625	14.23	15.87
B	0.380	0.420	9.66	10.66
C	0.140	0.190	3.56	4.82
D	0.025	0.035	0.64	0.89
F	0.139	0.155	3.53	3.93
G	0.100 BSC		2.54 BSC	
H	---	0.280	---	7.11
J	0.012	0.045	0.31	1.14
K	0.500	0.580	12.70	14.73
L	0.045	0.060	1.15	1.52
N	0.200 BSC		5.08 BSC	
Q	0.100	0.135	2.54	3.42
R	0.080	0.115	2.04	2.92
S	0.020	0.055	0.51	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045	---	1.15	---

D²PAK
3-PIN
DP SUFFIX
CASE 418E-01
ISSUE O



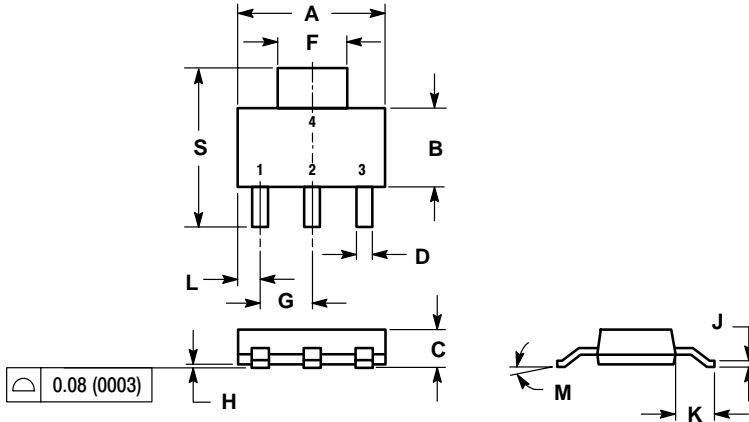
NOTES:

1. DIMENSIONS AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.326	0.336	8.28	8.53
B	0.396	0.406	10.05	10.31
C	0.170	0.180	4.31	4.57
D	0.026	0.036	0.66	0.91
E	0.045	0.055	1.14	1.40
F	0.090	0.110	2.29	2.79
G	0.100 BSC		2.54 BSC	
H	0.098	0.108	2.49	2.74
J	0.018	0.025	0.46	0.64
K	0.204	0.214	5.18	5.44
L	0.045	0.055	1.14	1.40
M	0.055	0.066	1.40	1.68
N	0.000	0.004	0.00	0.10

CS5201-3

SOT-223
ST SUFFIX
CASE 318E-04
ISSUE K




- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.249	0.263	6.30	6.70
B	0.130	0.145	3.30	3.70
C	0.060	0.068	1.50	1.75
D	0.024	0.035	0.60	0.89
F	0.115	0.126	2.90	3.20
G	0.087	0.094	2.20	2.40
H	0.0008	0.0040	0.020	0.100
J	0.009	0.014	0.24	0.35
K	0.060	0.078	1.50	2.00
L	0.033	0.041	0.85	1.05
M	0°	10°	0°	10°
S	0.264	0.287	6.70	7.30

PACKAGE THERMAL DATA

Parameter		TO-220 THREE LEAD	D ² PAK 3-PIN	SOT-223	Unit
R _{θJC}	Typical	3.5	3.5	15	°C/W
R _{θJA}	Typical	50	10-50*	156	°C/W

* Depending on thermal properties of substrate. $R_{\theta JA} = R_{\theta JC} + R_{\theta CA}$

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